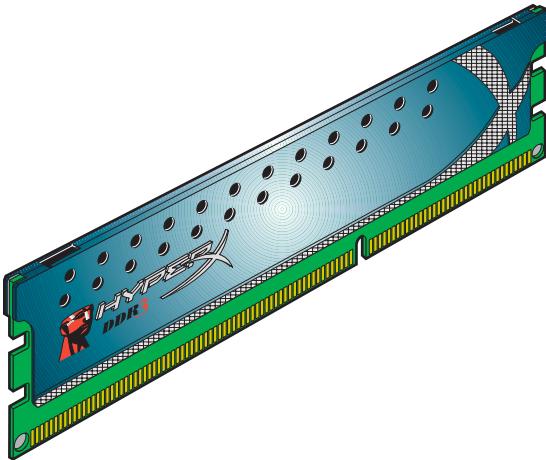


Memory Module Specifications

KHX2000C9AD3K3/3GX

3GB (1GB 128M x 64-Bit x 3 pcs.) DDR3-2000MHz

CL9 240-Pin DIMM Kit



SPECIFICATIONS

| | |
|--|--------------------------------|
| CL(IDD) | 9 cycles |
| Row Cycle Time (tRCmin) | 49.5ns (min.) |
| Refresh to Active/Refresh Command Time (tRFCmin) | 110ns |
| Row Active Time (tRASmin) | 36ns (min.) |
| Power | 1.080 W (operating per module) |
| UL Rating | 94 V - 0 |
| Operating Temperature | 0° C to 85° C |
| Storage Temperature | -55° C to +100° C |

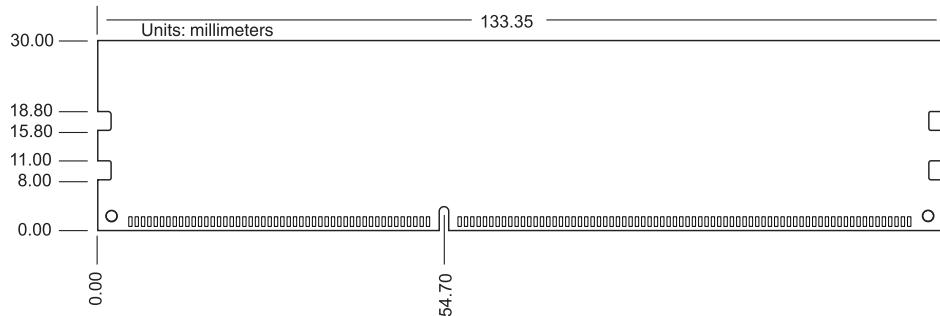
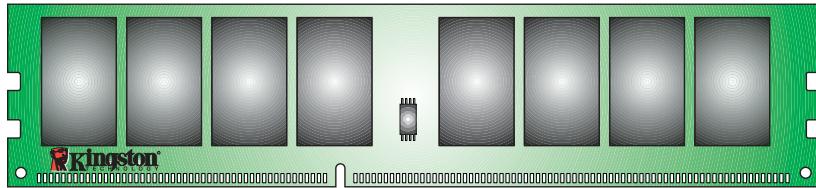
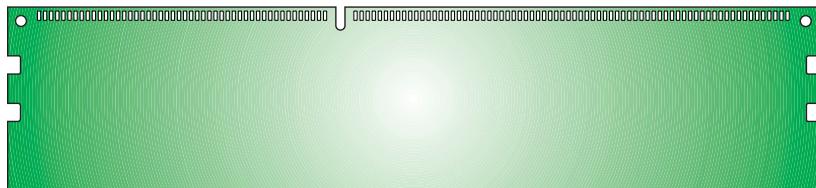
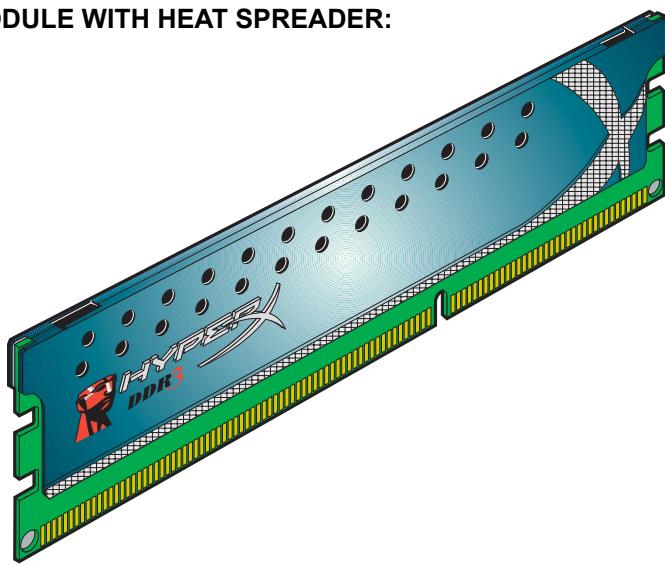
DESCRIPTION

Kingston's KHX2000C9AD3K3/3GX is a kit of three 128M x 64-bit 1GB (1024MB) DDR3-2000MHz CL9 SDRAM (Synchronous DRAM) memory modules, based on eight 128M x 8-bit DDR3 FBGA components per module. Each module kit supports Intel® XMP (Extreme Memory Profiles). Total kit capacity is 3GB. Each module kit has been tested to run at DDR3-2000MHz at a low latency timing of 9-10-9-27 at 1.65V. The SPDs are programmed to JEDEC standard latency DDR3-1333MHz timing of 9-9-9 at 1.5V. Each 240-pin DIMM uses gold contact fingers and requires +1.5V. The JEDEC standard electrical and mechanical specifications are as follows:

FEATURES

- JEDEC standard 1.5V ± 0.075V Power Supply
- VDDQ = 1.5V ± 0.075V
- 667MHz fCK for 1333Mb/sec/pin
- 8 independent internal bank
- Programmable CAS Latency: 5,6,7,8,9,10
- Posted CAS
- Programmable Additive Latency: 0, CL - 2, or CL - 1 clock
- Programmable CAS Write Latency(CWL) = 7(DDR3-1333)
- 8-bit pre-fetch
- Burst Length: 8 (Interleave without any limit, sequential with starting address "000" only), 4 with tCCD = 4 which does not allow seamless read or write [either on the fly using A12 or MRS]
- Bi-directional Differential Data Strobe
- Internal(self) calibration : Internal self calibration through ZQ pin (RZQ : 240 ohm ± 1%)
- On Die Termination using ODT pin
- Average Refresh Period 7.8us at lower than TCASE 85°C, 3.9us at 85°C < TCASE ≤ 95°C
- Asynchronous Reset
- PCB : Height 1.18" (30mm), single sided component

Continued >>

MODULE DIMENSIONS:**MODULE WITH HEAT SPREADER:**

FOR MORE INFORMATION, GO TO WWW.KINGSTON.COM

All Kingston products are tested to meet our published specifications. Some motherboards or system configurations may not operate at the published HyperX memory speeds and timing settings. Kingston does not recommend that any user attempt to run their computers faster than the published speed. Overclocking or modifying your system timing may result in damage to computer components.